Subt A' WHAT IS CLAIMED IS:

1. A semiconductor package comprising:

a first insulating substrate carrying a mounting portion for mounting a semiconductor device and a first electrically conductive pattern electrically connected to said semiconductor device;

a sidewall section formed upright around said mounting portion of said first insulating substrate;

a cavity defined by said first insulating substrate and the sidewall section and encapsulated by encapsulating resin as said semiconductor device is mounted on said mounting portion; and

a second insulating substrate provided in said cavity and on said sidewall section and carrying a second electrically conductive pattern electrically connected to said first electrically conductive pattern via through-holes formed in said sidewall section; wherein

solder lands are provided at least in said cavity on one surface of said first insulating substrate.

2. The semiconductor package according to claim 1 wherein a heat radiating plate is provided on the opposite surface of said first insulating substrate.

3. The semiconductor package according to claim 1 wherein said first insulating substrate is a laminated sheet lined on both sides with copper.

4. The semiconductor package according to claim 1 wherein said second insulating

substrate is a laminated sheet lined on one side with copper.

5. A method for the preparation of a semiconductor package comprising the steps of:

forming a mounting portion for mounting a semiconductor device and a first electrically conductive pattern for electrically connecting the semiconductor device on a first insulating substrate;

layering a spacer having an opening of substantially the same size as said mounting portion in one surface of said first insulating substrate;

mounting a semiconductor device in said mounting portion defined by said first insulating substrate and the opening provided in said spacer;

encapsulating said cavity with encapsulating resin after mounting said semiconductor device in said mounting portion;

layering a second insulating substrate carrying the electrically conductive layer on one surface thereof on said spacer;

forming a through-hole for establishing electrical connection between said first electrically conductive pattern and said electrically conductive layer; and

forming solder lands at least in said cavity in said electrically conductive layer.

6. The method according to claim 5 wherein said first insulating substrate is a laminated sheet lined on both sides with copper.

7. The method according to claim 5 wherein said second insulating substrate is a laminated sheet lined on one side with copper.

8. The method according to claim 5 further comprising:

providing a heat radiating plate on the opposite surface of said first insulating substrate after forming said second electrically conductive pattern.

add
a^2